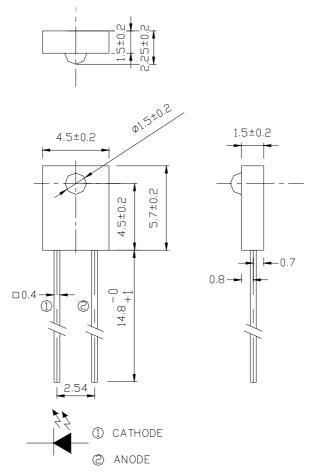




Package Dimensions



Notes: 1. All dimensions are in millimeters

2.Tolerances unless dimensions ±0.25mm

Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Units
Continuous Forward Current	$ m I_F$	50	mA
Peak Forward Current	I_{FP}	1.0	A
Reverse Voltage	V_R	5	V
Operating Temperature	T_{opr}	-25 ~ +85	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{stg}	-40 ~ +100	$^{\circ}\! \mathbb{C}$
Soldering Temperature	T_{sol}	260	$^{\circ}\!\mathbb{C}$
Power Dissipation at(or below) 25°C Free Air Temperature	P_d	75	mW

Notes: *1: I_{FP} Conditions--Pulse Width $\leq 100 \mu$ s and Duty $\leq 1\%$.

*2:Soldering time ≤ 5 seconds.

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Electro-Optical Characteristics (Ta=25℃)

Parameter	Symbol	ol Condition		Typ.	Max.	Units
Light Current	Ic(on)	$I_F=4\text{mA}, V_{CE}=3.5\text{V}$	143		1274	μ A
Peak Wavelength	λp	I _F =20mA		940		nm
Spectral Bandwidth	Δλ	I _F =20mA		45		nm
Forward Voltage	V_{F}	$I_F=20\text{mA}$		1.2	1.5	V
Reverse Current	I_R	$V_R=5V$			10	μ A
View Angle	2 θ 1/2	$I_F=20\text{mA}$		60		De g

Rank

Color Code	Ranks	Symbol	Min	Тур	Max	Unit	Test Condition
Red	E1	Ic(on)	143		255	μ A	$I_F=4\text{mA}, V_{CE}=3.5\text{V}$
Blue	E2	Ic(on)	214		343	μ A	$I_F=4\text{mA}, V_{CE}=3.5\text{V}$
Yellow	E3	Ic(on)	286		431	μ A	$I_F=4mA, V_{CE}=3.5V$
Silver	E4	Ic(on)	357		519	μ A	$I_F=4mA, V_{CE}=3.5V$
Green	E5	Ic(on)	428		608	μ A	I _F =4mA,V _{CE} =3.5V
Purple	E6	Ic(on)	500		696	μ A	I _F =4mA,V _{CE} =3.5V
White	E7	Ic(on)	571		784	μ A	I _F =4mA,V _{CE} =3.5V

Rough ranks

Parameter	Min	Max	Unit	Test Condition
7-2	306	441	μ A	$I_F=4\text{mA}, V_{CE}=3.5\text{V}$
7-1	347	550	μ A	I _F =4mA,V _{CE} =3.5V
6-2	465	750	μ A	$I_F=4\text{mA}, V_{CE}=3.5\text{V}$
6-1	650	1274	μ A	$I_F=4\text{mA}, V_{CE}=3.5\text{V}$

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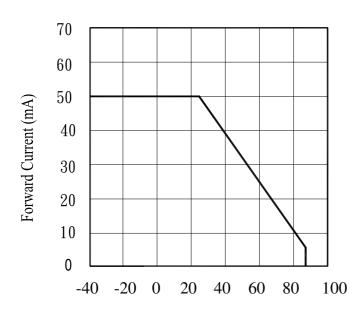


Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs.

Ambient Temperature

Fig.2 Spectral Distribution



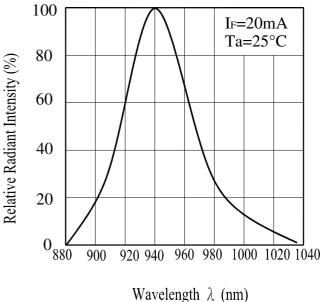
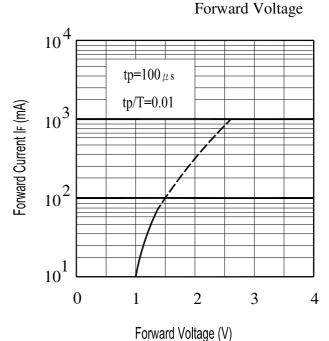


Fig.3 Peak Emission Wavelength vs.

Ambient Temperature

980
960
940
920
925
0
25
50
75
100
Ambient Temperature (°C)

Fig.4 Forward Current vs.



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Typical Electro-Optical Characteristics Curves

Fig.5 Forward Current vs.

Ambient Temperature (° C)

1.3

1.2

IF=20mA

1.1

25

50

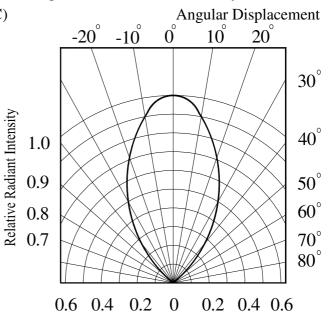
75

100

120

Ambient Temperature (° C)

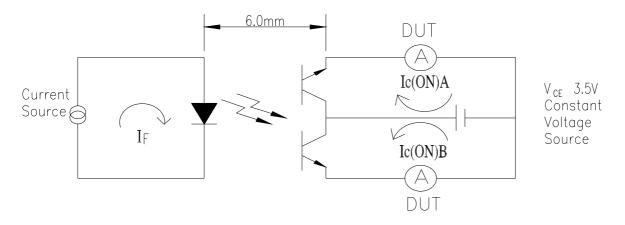
Fig.6 Relative Radiant Intensity vs.



Test Method For I_{C(ON)}:

Condition: I_F=4mA,V_{CE}=3.5V

The intensity testing method for infrared emitting diode



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Reliability Test Item And Condition

The reliability of products shall be satisfied with items listed below.

Confidence level: 90%

LTPD: 10%

NO.	Item	Test Conditions	Test Hours/	Sample	Failure	Ac/Re
			Cycles	Sizes	Judgement	
					Criteria	
1	Solder Heat	TEMP. : 260°C±5°C	10secs	22pcs		0/1
2	Temperature Cycle	$H: +100^{\circ}C$ 15mins	300Cycles	22pcs		0/1
		5mins				
		L: -40°C				
3	Thermal Shock	H :+100°C ▲ 5mins	300Cycles	22pcs		0/1
		▼ 10secs				
		L:- 10° C 5mins			Attenuation of	
4	High Temperature	TEMP. ∶ +100°C	1000hrs	22pcs	Light Current	0/1
	Storage				value>20%	
5	Low Temperature	TEMP. : -40°C	1000hrs	22pcs		0/1
	Storage			_		
6	DC Operating Life	I _F =20mA	1000hrs	22pcs		0/1
7	High Temperature/	85℃ / 85% R.H	1000hrs	22pcs		0/1
	High Humidity					

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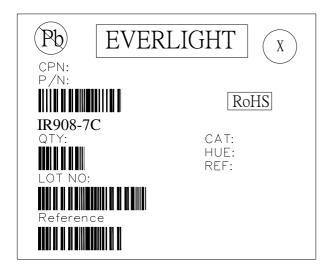
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Packing Quantity Specification

- 1. 1000PCS/1Bag,8Bag/1Box
- 2. 10Boxes/1Carton

Label Form Specification



CPN: Customer's Production Number

P/N: Production Number QTY: Packing Quantity

CAT: Ranks

HUE: Peak Wavelength

REF: Reference

LOT No: Lot Number

X: Month

Reference: Identify Label Number

Notes

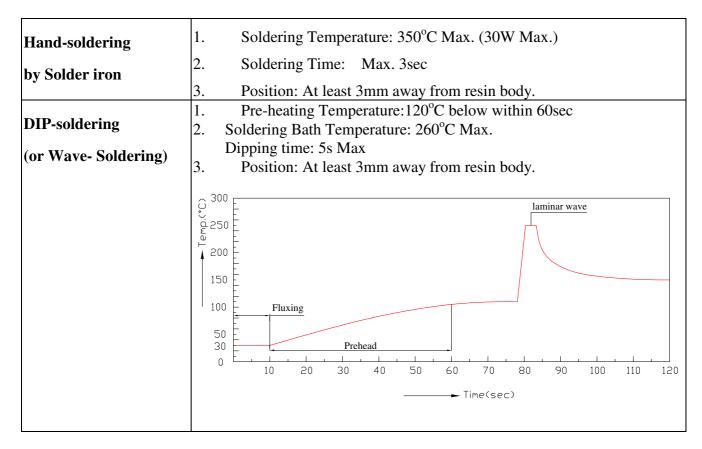
- 1. Above specification may be changed without notice. EVERLIGHT will reserve authority on material change for above specification.
- 2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
- 3. These specification sheets include materials protected under copyright of EVERLIGHT corporation. Please don't reproduce or cause anyone to reproduce them without EVERLIGHT's consent.



Application Note:

Through-Hole Type LED Soldering Condition

To avoid overheating and reliability concerns of through-hole type LEDs, below is our suggested soldering method :



Notice:

- 1. Avoiding applying any stress to the lead frame while the LEDs are at high temperature particularly when soldering.
- 2. Dip and hand soldering should not be done more than 1 time.
- 3. After soldering the LEDs, the epoxy resin should be protected from mechanical shock or vibration until the LEDs return to room temperature.

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A rapid-rate process is not recommended for cooling the LEDs down from the peak 4.

temperature.

Although the recommended soldering conditions are specified in the above table, dip or 5.

hand-soldering at the lowest possible temperature is desirable for the LEDs.

6. Wave soldering parameter must be set and maintain according to recommended

temperature and dwell time in the solder wave.

Cleaning

1. When necessary, cleaning should only use with isopropyl alcohol at room temperature for a

duration of no more than 1 minute. Dry at room temperature before use.

Do not clean the LEDs by the ultrasonic. When it is absolutely necessary, the influence of 2.

ultrasonic cleaning on the LEDs depends on factors such as ultrasonic power and the

assembled condition. (Please refer to below reference condition.)

Notice: (1) This bonding wire in the package can have an effect on the resonance reliability.

Please not touch the vibrating source directly. Ultrasonic cleaning shall be

pre-qualified to ensure this will not cause damage to the LED

(2) Reference condition: Refer to JEITA Standard Test requirement

a. Ultrasonic Wave Frequency: 25KHz±4KHz or 40 KHz (+8 KHz/-4KHz)

b. Output: 10W/Litre ~30W/Litre

c. Duration: 60s±5S, Temperature: under 40°C

Drying should be performed under 90°C and 30s.

Both cleaning and Drying should not be performed over 4 times.

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